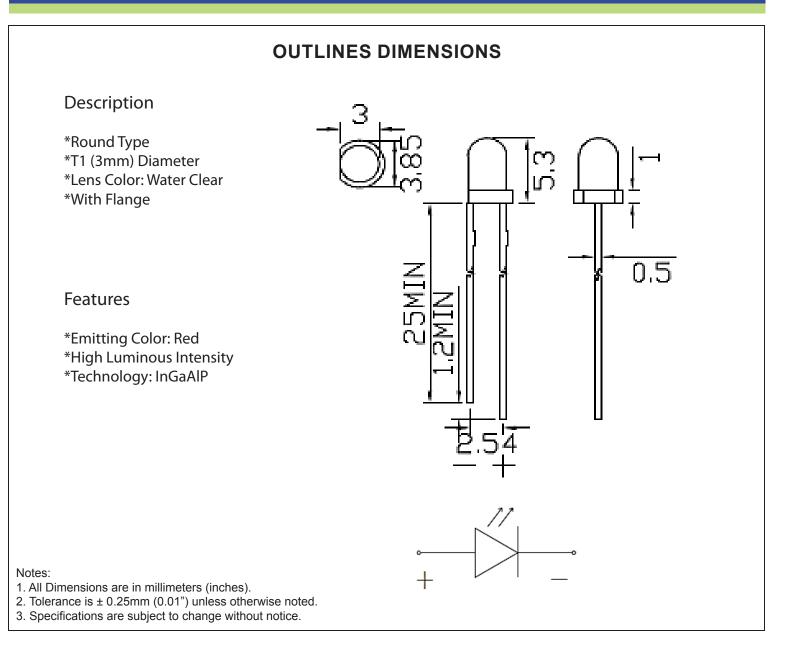


SPECIFICATIONS



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CLA30R2C	InGaAIP	Red	Water Clear	20°



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CLA30R2C



ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Power Dissipation	PD	60	mW	
Pulse Current Forward Current	lfp	60	mA	
Continuous Forward Current	lF	30	mA	
Reverse Voltage	VR	5	V	
Operating Temperature Range	Topr	-25~+85	°C	
Storage Temperature Range	Тѕтс	-30~+85	°C	
IFP = Pulse Width \leq 10 ms, Duty Ratio \leq 1/10. Soldering Condition: 260 °C/ 5sec				

OPTICAL-ELECTRICAL CHARACTERISTICS

Value **Test Condition** Parameter Symbol Unit Min Тур Max 1000 1500 Luminous Intensity Iv I_F = 20mA _ mcd Forward Voltage I⊧ = 20mA 2.1 2.4 V VF _ 10 **Reverse Leakage Current** $V_R = 5V$ _ IR _ μA **Viewing Angle** $2\theta 1/2$ I_F = 20mA 20 _ _ deg I⊧ = 20mA 640 630 **Dominant Wavelength** _ λD nm

*Tolerance of viewing angle: -10 / +5 deg.

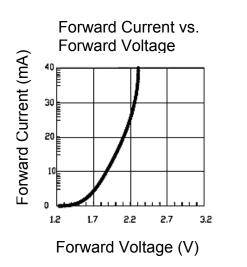


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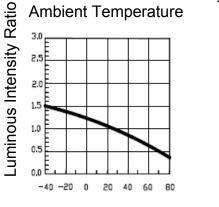
(TA=25°C)



OPTICAL CHARACTERISTIC CURVES



Relative Luminous Intensity vs. **Ambient Temperature**

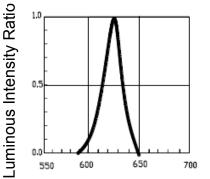


Ambient Temperature (°C)

Forward Current vs. **Relative Luminous Intensity** Luminous Intensity Ratio ^{3.0} E 2.5 2.0 1.5 1.0 0,5 ٥ 10 20 30 40 50

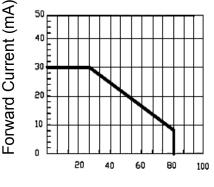
Forward Current (mA)

Relative Luminous Intensity vs. Main Wavelength

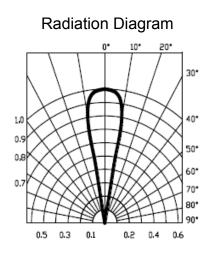


Dominant Wavelength (nm)

Forward Current vs. **Ambient Temperature**



Ambient Temperature (°C)





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SOLDERING CONDITIONS – LAMP TYPE LED

* Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.

* Recommended soldering conditions

Dip Soldering			
Pre-Heat	100 °C Max		
Pre-Heat Time	60 Second Max		
Solder Bath Temperature	260 °C Max		
Dippng Time	5 Second Max		
Dipping Position	No lower than 3mm from the base of the epoxy		

Hand Soldering				
	3mm Series	Others		
Temperature Soldering Time Position	300 °C Max 3 Second Max No closer than 3mm from the base of the epoxy	350 °C Max 3 Second Max No closer than 3mm from the base of the epoxy		

* Do not apply any stress to the lead. Particularly when heated.

- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.



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